

KESTER® 959 SOLDERING FLUX

Low-Solids, No-Clean Liquid Flux

DESCRIPTION

Kester 959 soldering Flux is a no-clean, non-corrosive, liquid flux that is designed for the wave soldering of conventional and surface mount circuit board assemblies. 959 was developed to minimize the formation of micro-solder balls during wave soldering operations. This flux contains a small percentage of rosin (1%), which improves solder-ability, heat stability and surface insulation resistance. 959 offers the best wetting and the shiniest solder joints of any no-clean, solvent-based chemistry. It is a very good flux that can be used for secondary soldering such as touch up and repair. 959 leaves evenly distributed residues for the best cosmetic appearance.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

FEATURES & BENEFITS

- Minimize micro-solderballs
- Extremely shiny joints
- No streaky, white residues
- Improves soldering performance
- Eliminates the need and expense of cleaning
- Classified as ORL0 per J-STD-004

ROHS COMPLIANCE

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2015/863 for the stated banned substances.

TECHNICAL DATA

Category	Results	Procedure/Remarks
Physical Properties		
Specific Gravity	0.810 ± 0.005	Anton Paar DMA 35 @ 25 °C
Percent Solids (typical)	3.9%	Tested to J-STD-004, IPC-TM-650, Method

Category	Results	Procedure/Remarks		
Acid Number	21.8 ± 1.5 mg KOH/g of flux	Tested to J-STD-004, IPC-TM-650, Method 2.3.13		
pH (10% solution)	4.6	Hanna Instruments 8314 @ 25 °C		
Thinner	4662			
Reliability Properties				
Copper Mirror Corrosion	Low	Tested to J-STD-004, IPC-TM-650, Method 2.3.32		
Corrosion Test	Low	Tested to J-STD-004, IPC-TM-650, Method 2.6.15		
Silver Chromate	Pass	Tested to J-STD-004, IPC-TM-650, Method 2.3.33		
Chloride and Bromides	None Detected	Tested to J-STD-004, IPC-TM-650, Method 2.3.35		
Fluorides by Spot Test	Pass	Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1		
Surface Insulation Resistivity (SIR), IPC (Typical)	Pass	Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3		
		Blank	959 PD	959 PU
	Day 1	2.7*10 ¹⁰ Ω	2.4*10 ¹⁰ Ω	2.4*10 ¹⁰ Ω
	Day 4	1.5*10 ¹⁰ Ω	1.5*10 ¹⁰ Ω	1.4*10 ¹⁰ Ω
	Day 7	1.2*10 ¹⁰ Ω	1.2*10 ¹⁰ Ω	1.1*10 ¹⁰ Ω

PROCESSING GUIDELINES

Process Considerations / Recommendations

The optimum preheat temperature for most circuit assemblies is 90 to 105 °C (194 to 221 °F) as measured on the top or component side of the printed circuit board. Dwell time in the wave is typically 2 to 4 seconds for leaded alloys, and 4 to 8 seconds for lead-free alloys. The conveyor speed should be adjusted to accomplish proper board contact time with the solder. Then the preheat temperatures are adjusted to achieve the required preheat top board temperatures. In the event you need further direction on the setup of your wave soldering system, please contact MacDermid Alpha Technical Support.

Flux Control

Acid number is normally the most reliable method to control the flux concentration of low solids, no clean fluxes. To check concentration, a simple acid-base titration should be used. PS-22 Test Kit and procedure are available from MacDermid Alpha. Control of the flux in the foam flux tank during use is necessary for assurance of consistent flux distribution on the circuit boards. The complex nature of the solvent system for the flux makes it imperative that Kester 4662 Thinner be used to replace evaporative losses. When excessive debris from circuit boards, such as board fibers and from the airline build-up in the flux tank, these particulates will redeposit on the circuit boards which may create a build-up of residues on probe test pins. It is, therefore, necessary to clean the tank and then replenish it with fresh flux when excessive debris accumulates in the flux tank.

Cleaning

959 flux residues are non-conductive, non-corrosive and do not require removal in most applications. If residue removal is required, consult MacDermid Alpha Technical Support for further cleaning recommendation.

Storage, Handling and Shelf Life

959 is flammable. Store away from sources of ignition. Shelf life is 2 years from the date of manufacture when handled properly and held at 10 to 25 °C (50 to 77 °F).

AVAILABILITY

959 can be applied to circuit boards by a spray, foam or dip process. Flux deposition should be 120 to 240 µg of solids/cm² (750 to 1500 µg of solids/in²). An air knife after the flux tank is recommended in a foam and wave application to remove excess flux from the circuit board and prevent dripping on the preheated surface.

RECYCLING SERVICES

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams.

Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area.



SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available.**

CONTACT INFORMATION

www.macdermidalpha.com

<p>North America 140 Centennial Avenue Piscataway, NJ 08854 1.800.367.5460</p>	<p>Europe Unit 2, Genesis Business Park Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400</p>	<p>Asia 8/F., Two Sky Parc 51 Hung To Road Kwun Tong, Kowloon, Hong Kong, SAR China 852.2500.5365</p>
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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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